

Normally-Off GaN-PSJ FETs

POWDEC K.K.

Shoko Hirata, S. Matsumoto, K. Ichimaru, T. Saito, S. Yagi, F. Nakamura and H. Kawai

E-mail: info@powdec.co.jp

[1. Background]

The high V_B , collapse-free and high current GaN PSJ (Polarization super-junction) FETs have been fabricated and the next step will be the realization of the N-off mode ones.

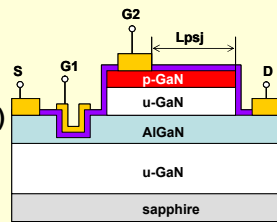
[2. Purpose]

To achieve GaN PSJ-FETs having V_{th} higher than +1V and $V_B > 1,200V$

[4. N-off Device Structure]

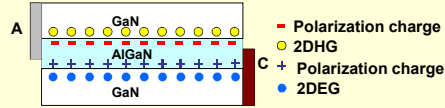
Double Gates

- G1, MIS, $L_{g1}=1.5\mu m$
Au.Ni/SiN(10nm)/AlGaIn(1~3nm)
- G2, p-Ohmic, $L_{g2}=5\mu m$
- $L_{psj}=15\mu m$

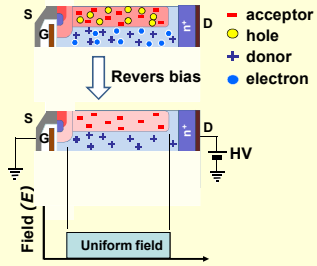


[3. What PSJ (Polarization Super-Junction) is] Comparison with Si super-junction

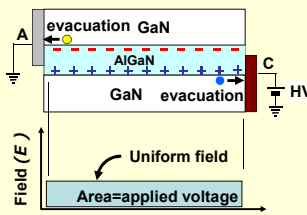
GaN/AlGaIn/GaN Polarization Super-junction (PSJ)



Si super-junction MOS (one pillar)



Applying reverse bias
evacuation of 2DHG and 2DEG

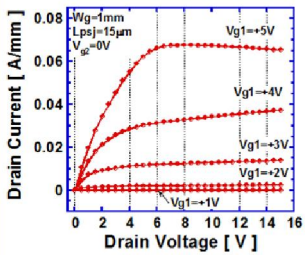


Contrast GaN-PSJ with Si-SJ

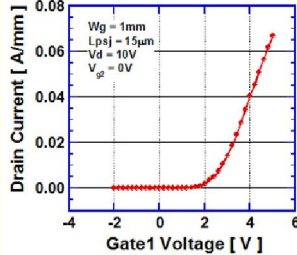
	GaN-PSJ	Si-SJ
Formation	Surface (Lateral) GaN/AlGaIn/GaN	Inside (Vertical) p/n pillar stack
Origin of carriers	polarization	impurity doping
Thickness	A few 10s nm	A few μm

[5. Static Characteristics]

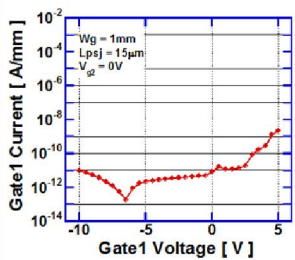
($W_g=1mm, L_{g1}=1.5\mu m$)



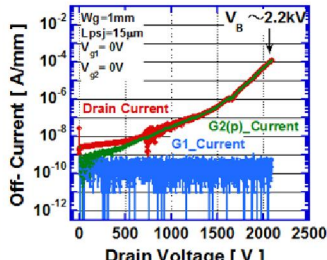
Id-Vd characteristics.



Transfer characteristics.



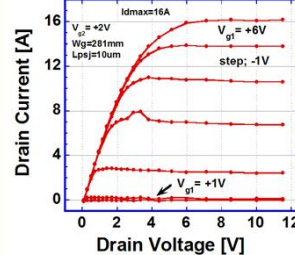
Gate-leak characteristics.



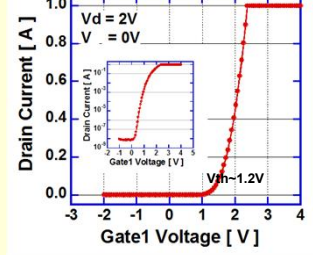
Off-leak characteristics.

[6. Large Device]

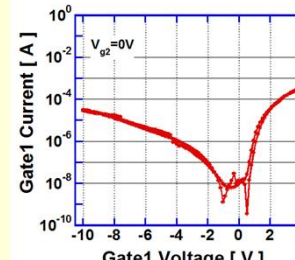
($W_g=281mm, L_{g1}=1.5\mu m$)



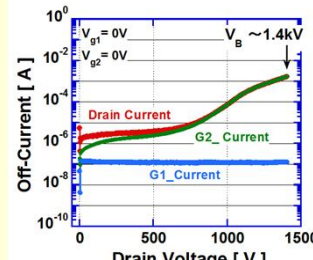
Id-Vd characteristics.



Transfer characteristics.



Gate-leak characteristics.



Off-leak characteristics.

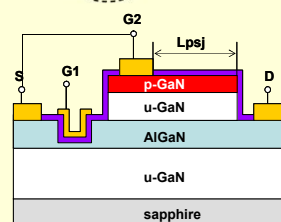
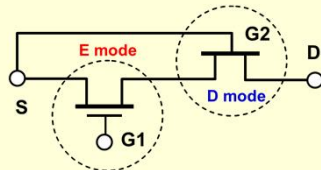
[7. Discussion]

-- Both Normally-off and high V_B obtained result from the formation of the Cascode circuit between source and drain.

-- The field in the AlGaIn next to the G1 is kept small with increasing drain voltage, which results in the constant and small G1 leakage current.

-- The drain leakage was originated from the G2-leakage due to the unknown mechanism.

built-in Cascode



[8. Summary]

1. N-off type PSJ-FET was achieved by implementing a trench MIS gate in front of the PSJ gate, and its V_{th} obtained was $>+1$ Volt.
2. The large device with $W_g=281mm$ and $L_g=1.5\mu m$ exhibited the maximum drain current, $I_{d,max}$ of 16A.
3. The breakdown voltage, V_B , of the small device ($W_g=1mm$) was >2.2 kV and that of the large one ($W_g=281mm$) was $>1.4kV$.

[9. Conclusions]

1. The double gate N-off PSJ-FET exhibited very high breakdown voltage due to the internal Cascode conformation.
2. GaN PSJ-devices using established GaN-on-sapphire growth technique are expected to become a new type of GaN power devices.